Jiashen Du

Curriculum Vitae

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EDUCATION

ShanghaiTech University, Shanghai, China   2022.09 - 2026.06 (Expected)
Sophomore, Computer Science
- Total GPA: 3.35/4.0
- TOEFL: 107/120
- Strength: Introduction to Machine Learning (final project scored 100/100), American Dreams (scored highest in class after curved), and Introduction to Interactive Design.

RESEARCH AND WORK EXPERIENCE

VRVC Lab, Frontier Base, ShanghaiTech University ———— 2023.02 - Present
Undergraduate Research Intern — Shanghai, China
Highly involved in the work of the subject group, conducting and participating in research related to 3D Human-Object-Interaction reconstructions. Previous work has been accepted by CVPR 2024 and mainly focuses on fusing LLMs with traditional computer vision methods now.

Shanghai Elan Smart Sense Information Technology Co.,LTD. ———— 2023.04 - Present
Deputy researcher of Research Team & Head of Motion Capture Team — Shanghai, China
Modified and refined the previous work of 4D-Association Graph. Implemented a fully regressive way to recover human poses from a single RGB image, then refined and showed up in I'M HOI. Acknowledged and benchmarked various motion capture reconstruction methods like MVPose, OpenPose, and SMPLify-X. Helped set up the motion capture environment and taught new lab members about the prerequisites and the procedure of motion capturing. Designed and contributed to the $IMHD^2$ dataset in CVPR 2024.

Tutor, Shanghai, China ———— 2023.01 - 2023.03
Guided a high school student to attend China Youth Science and Creativity Contest, and taught a high school student English.

PUBLICATIONS

Conference Proceedings
I'M HOI: Inertia-aware Monocular Capture of 3D Human-Object Interactions
Chengfeng Zhao, Juze Zhang, **Jiashen Du**, Ziwei Shan, Junye Wang, Jingyi Yu, Jingya Wang, Lan Xu.
arXiv preprint arXiv:2312.08869. Now accepted by The IEEE/CVF Conference on Computer Vision and Pattern Recognition(CVPR). 2024

AWARDS AND HONORS

CUMCM: Chinese University Mathematical Contest in Modeling
The third prize
Year: 2023

ACTIVITIES AND SKILLS

ACTIVITIES
President of ShanghaiTech HiFi Research Club ———— 2023.05 - Present
Organized events and club activities, such as going to the audio expos. Designing special amplifiers and leading club members to finish annual projects like replicating discontinued HiFi products and making electrostatic headphones. Being invited to host a lecture about headphone and IEM design at the school technology festival.

SKILLS
Programming Skills: Python(Proficient), C++(Competent), C(Competent), Rust(Familiar with), MAT-LAB(Familiar with)
Language Skills: English(Fluent), Chinese(Native)
Other skills: Amplifier design(Familiar with), PCB routing(Familiar with), 3D printing(Familiar with)